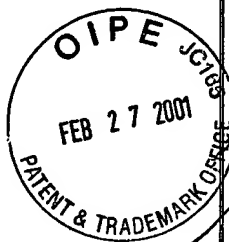


03-01-01

GAU 2831

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



Applicant: Glenn, Thomas P.  
Assignee: Amkor Technology, Inc.  
Title: Plastic Integrated Circuit Package And Method And Leadframe For Making The Package  
Serial No.: 09/615,107 Filing Date: 7/13/00  
Examiner: C. Oliva Group Art Unit: 2831  
Docket No.: M-5599-2D US

#9/dupr IPS  
DEVANS  
3/20/01San Jose, California  
February 27, 2001COMMISSIONER FOR PATENTS  
Washington, D. C. 20231SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT  
UNDER 37 CFR § 1.97(b)

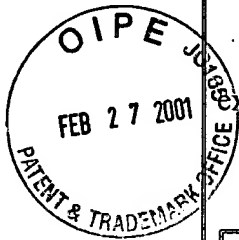
Dear Sir:

Pursuant to 37 C.F.R. § 1.56, § 1.97 and § 1.98, Applicant wishes to call the following documents listed on the accompanying PTO form 1449 to the Examiner's attention. Copies of the documents are enclosed.

Citation of the above documents shall not be construed as:

1. an admission that the documents are necessarily prior art with respect to the instant invention;
2. a representation that a search has been made, or
3. an admission that the information cited herein is, or is considered to be, material to patentability as defined in § 1.56(b).

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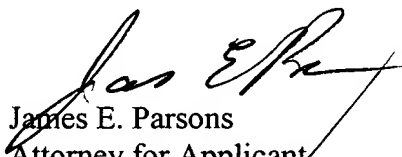


Applicant believes that no fee is necessary, since the case has not be substantively examined. However, any appropriate fees may be charged to Deposit Account No. 19-2386.

EXPRESS MAIL LABEL NO:

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Respectfully submitted,



James E. Parsons  
Attorney for Applicant  
Reg. No. 34,691

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